

Title (en)

Method for forming thick film layer of micro injecting device

Title (de)

Verfahren zum Bilden einer Dickfilmschicht für Mikrospritzvorrichtung

Title (fr)

Procédé de formation d'une couche à film épais pour micro-dispositif d'injection

Publication

EP 0999057 A3 20001129 (EN)

Application

EP 99308721 A 19991103

Priority

RU 98119888 A 19981103

Abstract (en)

[origin: EP0999057A2] A method for forming a thick film layer (30) of micro injecting device is disclosed in which a thin film layer (31') is formed on a substrate (1), a thick film layer (32') is formed on the thin film layer (31') without performing additional heat-treatment, and the thin film layer (31') and thick film layer (32') formed sequentially on the substrate are simultaneously heat-treated, to thereby complete a single thick film layer (30). The single thick film layer (30) is formed by a sequential coating process without being interfered by heat-treatment, thereby eliminating an isolating line. As a result, an overall durability of thick film layer (30) can be significantly enhanced. <IMAGE>

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IPC 8 full level

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CPC (source: EP KR)

B41J 2/04 (2013.01 - KR); **B41J 2/14032** (2013.01 - EP); **B41J 2/1603** (2013.01 - EP); **B41J 2/1626** (2013.01 - EP); **B41J 2/1645** (2013.01 - EP)

Citation (search report)

- [X] US 5450108 A 19950912 - DRAKE DONALD J [US], et al
- [A] US 5682187 A 19971028 - WATANABE TAKASHI [JP], et al
- [A] US 4267212 A 19810512 - SAKAWAKI SHINICHI

Cited by

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